



Material Content Data Sheet



Sales Product Name	TLE6251DS			Issued	7. August 2019			
MA#	MA001729592							
Package	PG-DSO-8-16			Weight*	83.64 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.755	4.49	4.49	44890	44890
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		107	
	non noble metal	zinc	7440-66-6	0.036	0.04		429	
	non noble metal	iron	7439-89-6	0.717	0.86		8575	
wire	non noble metal	copper	7440-50-8	29.121	34.82	35.73	348172	357283
	noble metal	gold	7440-57-5	0.201	0.24	0.24	2399	2399
	encapsulation	organic material	carbon black	1333-86-4	0.093	0.11		1117
encapsulation	plastics	epoxy resin	-	4.299	5.14		51401	
	inorganic material	silicondioxide	60676-86-0	42.337	50.62	55.87	506183	558701
leadfinish	non noble metal	tin	7440-31-5	0.814	0.97	0.97	9730	9730
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7774	7774
glue	plastics	acrylic resin	-	0.354	0.42		4229	
	noble metal	silver	7440-22-4	1.254	1.50	1.92	14994	19223
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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